

Surface Mount Thin-Film Filters

50Ω DC to 40 GHz

The Big Deal

- Low passband insertion loss
- High rejection
- Good power handling
- Temperature stability -55°C to 125°C
- High repeatability
- RoHS complaint
- Small size



Product Overview

Mini-Circuits' *Surface Mount Thin-Film filters* offer low insertion loss and high rejection realized via Thin-Film on Alumina substrate, using a sputtering process that can guarantee an enhanced Q and repeatable performance.

Low pass, high pass and bandpass surface mount thin-film designs can be realized with this technology. Using thin-film manufacturing, we can guarantee repeatability on large batches of filters. Thin-film filters are small in size with high-quality, precise machining for applications where size is critical.

Key Features

Feature	Advantages
Low insertion loss	High Q material and sputtering process results in lower insertion loss, better SNR is obtained.
Fast roll-off (steeper skirts)	High selectivity results in better adjacent channel rejection and dynamic range
Wider stopband	Wide spur-free stopband results in better adjacent channel rejection and dynamic range
Temperature stability	Very minimal change in electrical performance across temperature makes these filters suitable for a wide range of operating conditions.
Small Size	Various design techniques are employed to realize small size.

Notes

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Surface mount Thin Film Bandpass Filter

ABF-28G+

50Ω 26500 to 29500 MHz



Generic photo used for illustration purposes only
CASE STYLE: VG3044

Features

- Low mid band insertion loss of 1.6 dB typ.
- 15 dB typ. return loss in entire passband
- 60 dB typ. rejection
- Shielded component

Applications

- n257
- 5G Telecommunication

Electrical Specifications⁽¹⁾ at 25°C

Parameter		F#	Frequency (MHz)	Min.	Typ.	Max.	Unit
Pass Band	Center Frequency	Fc	28000	—	1.6	3.0	dB
	Insertion Loss	F1-F2	26500 - 29500	—	3.5	—	dB
Stop Band, Lower	Return Loss	F1-F2	26500 - 29500	—	15	—	dB
	Insertion Loss	DC-F3	DC - 23000	30	45	—	dB
Stop Band, Upper	Insertion Loss	F3-F4	23000 - 24500	25	45	—	dB
	Insertion Loss	F5-F6	31500 - 32500	25	55	—	dB
	Insertion Loss	F6-F7	32500 - 36000	40	60	—	dB
Stop Band, Upper	Insertion Loss	F7-F8	36000 - 40000	—	40	—	dB

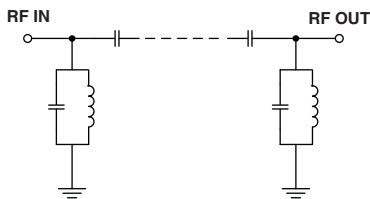
1. Measured on Mini-Circuits Characterization Test Board TB-ABF-28G+

Maximum Ratings

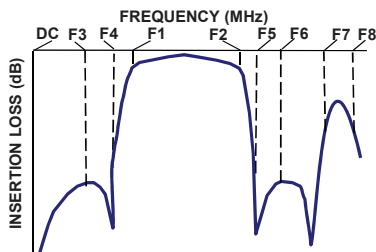
Operating Temperature	-55°C to 125°C
Storage Temperature	-55°C to 125°C
RF Power Input	1W Max. @ 25°C

Permanent damage may occur if any of these limits are exceeded.

Functional Schematic



Typical Frequency Response

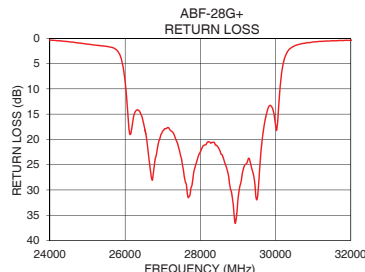
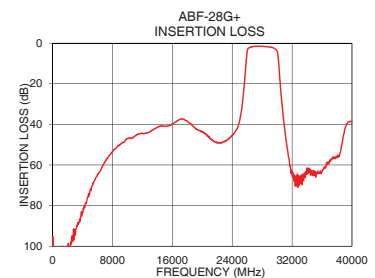
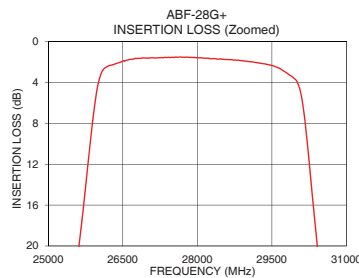


Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB)	Return Loss (dB)
10	107.70	0.03
1000	104.11	0.19
10000	47.03	0.07
23000	48.45	0.06
24500	43.04	0.68
25350	29.81	1.47
25600	20.76	1.72
26100	2.78	17.77
26500	1.92	17.16
27000	1.63	18.35
28000	1.58	22.45
29000	1.93	31.81
29500	2.33	31.96
29800	3.07	13.85
30425	20.51	1.83
30650	30.02	1.14
31500	55.78	0.48
32500	65.52	0.34
36000	63.14	0.06
40000	38.60	1.13

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications



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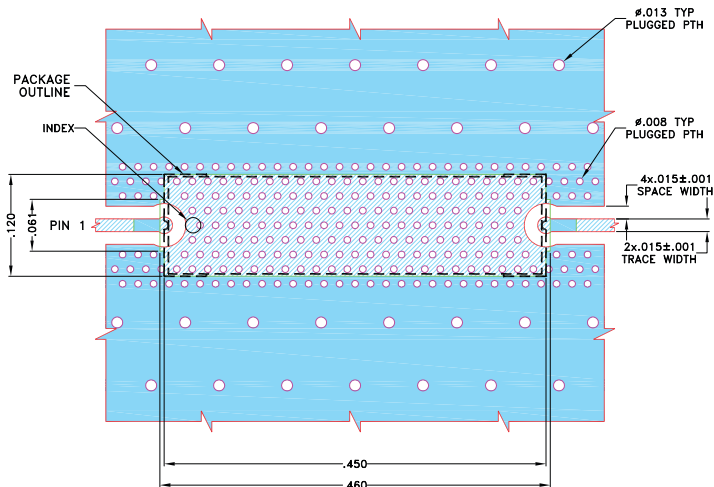


Pad Connections

RF IN	1
RF OUT	2
GROUND	3

Demo Board MCL P/N: TB-ABF-28G+
Suggested PCB Layout (PL-713)

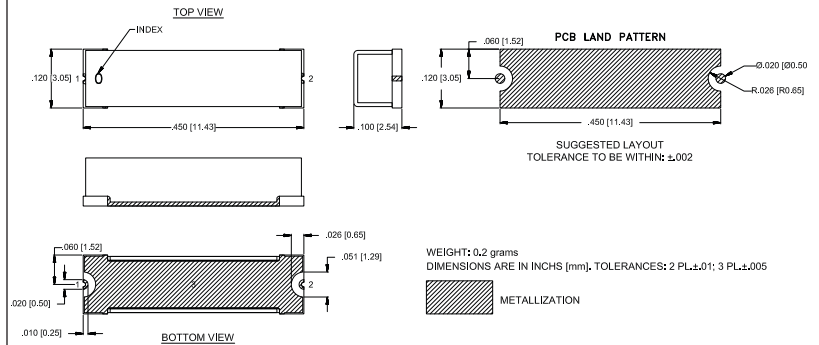
SUGGESTED MOUNTING CONFIGURATION FOR VG3044 CASE STYLE



NOTES:

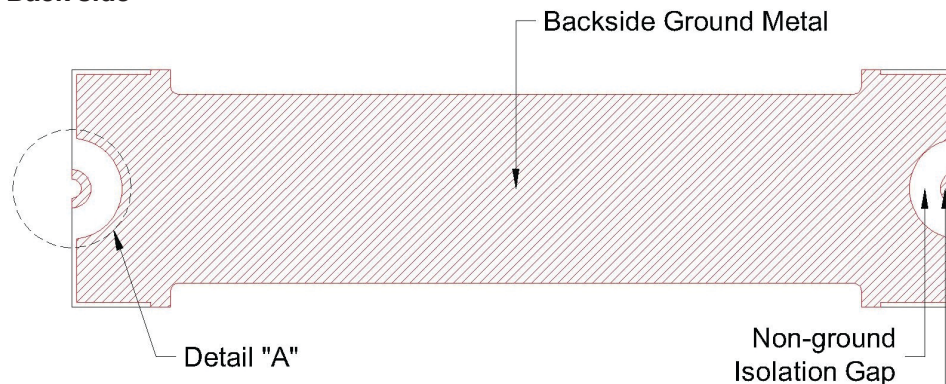
1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (RO4350B) WITH DIELECTRIC THICKNESS .0066±.0007. COPPER: 1/2 Oz. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
- DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)
 DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

Outline Drawing



Recommendations of PCB pattern at customer board

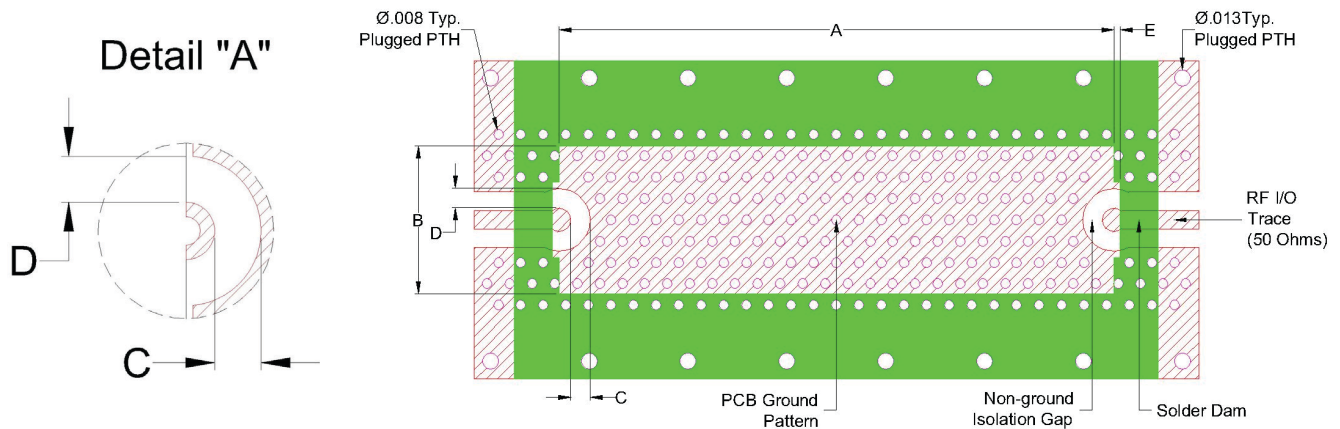
Filter Back side



I/O realized through a castellated via that mates directly to I/O pad on top of test board PCB

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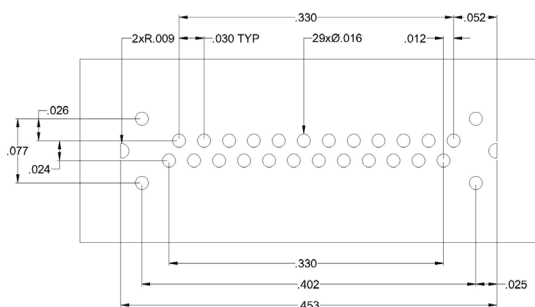


- 1) Customer PCB's ground pattern length (dimension A) can be similar to filter length.
- 2) Customer PCB's ground pattern width (dimension B) can be similar filter width.
- 3) Dimensions C and D on Filter RF I/O detail and Customer PCB pattern can be closely match. The dimensions of C and D on the Customer PCB pattern can be slightly larger to account for component alignment tolerance (ground metal can be pulled back from RF I/O trace).
- 4) Recommend to use solder mask at Customer PCB at outer area of filter pattern/footprint without any clearance.
- 5) Recommended to use Solder mask at I/O of Customer PCB with 5 mil clearance from filter I/O edge (dimension E)

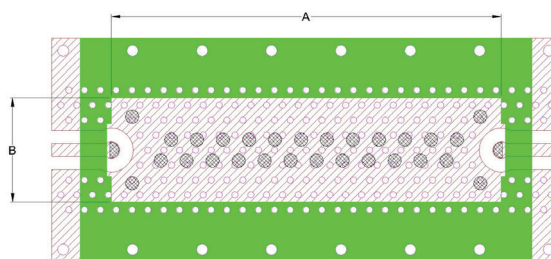
Comments on component handling and solder attach

- 1) Avoid using soldering iron directly to the ceramic filter. This would lead to development of crack in the component due to thermal shock.
- 2) Vacuum pick-up tool or plastic tweezers are recommended for handling the components. Extra care should be taken not to scratch the filter or metal area.
- 3) Use 2-3 mil thickness stencil plate and screen print the solder. Refer below picture for recommended stencil pattern to get the best solder attachment.

Stencil opening drawing



Solder location after screen print



- 4) Plugged ground vias in the PWB will improve attachment consistency.
- 5) Recommended to have a similar or closer test board material and thickness (refer Mini-Circuits evaluation board for details) to minimize the CTE over the temperature range.

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